

Global PCB Encapsulation Market Size Study & Forecast, by Resin Type, Curing Type, Application, and Regional Forecasts 2025–2035

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Abstracts

The Global PCB Encapsulation Market is valued at approximately USD 2.36 billion in 2024 and is projected to grow with a CAGR of 5.80% over the forecast period from 2025 to 2035. As the world pivots toward enhanced device reliability and miniaturization, PCB encapsulation has become an indispensable pillar in modern electronics manufacturing. These materials serve a critical function by safeguarding delicate circuit boards against environmental threats such as moisture, dust, chemicals, and thermal stress—essential in mission-critical applications spanning consumer electronics to medical and automotive technologies. Encapsulation not only preserves component integrity but also extends product life cycles, aligning perfectly with evolving industry demands for quality assurance and performance durability.

Market expansion is primarily fueled by a surge in demand for rugged and high-performance electronics, especially in smart wearables, medical implants, autonomous vehicles, and advanced industrial systems. In particular, epoxy resins have emerged as a go-to solution for their superior mechanical strength and adhesion properties, while acrylics are being favored for their optical clarity and fast cure times. Simultaneously, technological advancements in UV- and heat-curable encapsulation processes are revolutionizing production lines, enabling quicker turnaround times and higher throughput. The electronics manufacturing sector is also witnessing rising preferences for sustainable encapsulation materials with low VOC emissions, as regulatory bodies impose tighter restrictions globally.

Regionally, North America currently leads the PCB encapsulation space, backed by a robust base of electronics and semiconductor manufacturing, particularly in the United States. Its dominance is further reinforced by substantial investments in military-grade

and aerospace electronic systems, where protective encapsulation is non-negotiable. Meanwhile, Europe is actively advancing green encapsulation chemistry, driven by strict environmental mandates and strong R&D funding, especially in Germany and the Nordic nations. On the other hand, Asia Pacific is poised to be the fastest-growing market during the forecast period. Countries like China, South Korea, and Taiwan are experiencing exponential growth in electronics production, driven by a thriving consumer electronics market, favorable governmental incentives, and global shifts in manufacturing hubs. India is also emerging as a formidable player with its increasing presence in electronics design and fabrication, further propelling regional demand.

Major market player included in this report are:

BASF SE

3M Company

Dow Inc.

Henkel AG & Co. KGaA

Huntsman Corporation

Hitachi Chemical Co., Ltd.

H.B. Fuller Company

Sika AG

Electrolube

LORD Corporation

Epic Resins

Parker Hannifin Corporation

Chase Corporation

Shin-Etsu Chemical Co., Ltd.

Dymax Corporation

Global PCB Encapsulation Market Report Scope:

Historical Data – 2023, 2024

Base Year for Estimation – 2024

Forecast period – 2025-2035

Report Coverage – Revenue forecast, Company Ranking, Competitive Landscape, Growth factors, and Trends

Regional Scope – North America; Europe; Asia Pacific; Latin America; Middle East & Africa

Customization Scope – Free report customization (equivalent up to 8 analysts' working hours) with purchase. Addition or alteration to country, regional & segment scope*

The objective of the study is to define market sizes of different segments & countries in recent years and to forecast the values for the coming years. The report is designed to incorporate both qualitative and quantitative aspects of the industry within the countries involved in the study. The report also provides detailed information about crucial aspects, such as driving factors and challenges, which will define the future growth of the market. Additionally, it incorporates potential opportunities in micro-markets for stakeholders to invest, along with a detailed analysis of the competitive landscape and product offerings of key players.

The detailed segments and sub-segments of the market are explained below:

By Resin Type:

Acrylic

Epoxy

By Curing Type:

UV-Cure

Heat Cure

Room Temperature Cure

By Application:

Consumer Electronics

Automotive Electronics

Medical Devices

By Region:

North America

U.S.

Canada

Europe

UK

Germany

France

Spain

Italy

Rest of Europe

Asia Pacific

China

India

Japan

Australia

South Korea

Rest of Asia Pacific

Latin America

Brazil

Mexico

Middle East & Africa

UAE

Saudi Arabia

South Africa

Rest of Middle East & Africa

Key Takeaways:

Market Estimates & Forecast for 10 years from 2025 to 2035.

Annualized revenues and regional level analysis for each market segment.

Detailed analysis of geographical landscape with Country level analysis of major regions.

Competitive landscape with information on major players in the market.

Analysis of key business strategies and recommendations on future market approach.

Analysis of competitive structure of the market.

Demand side and supply side analysis of the market.

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